

CLAD TARGET MATERIAL FOR SPUTTERING

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- **European:** C23C14/34B

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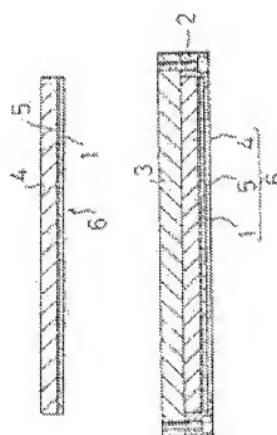
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Abstract of JP 1096374 (A)

PURPOSE: To prevent a clad target from

thermally adhering to a backing plate by
cladding a high-purity copper sheet
containing trace amounts of specific
elements with a sputtering target material.

CONSTITUTION: A Cu sheet 4 having
 $\geq 99.7\%$ purity and containing 100-
3,000wt. ppm, in total, of at least one or
more elements among Zn, In, Mn, Sb, Be,
Ca, Cr, Te, Y, Nb, Mo, Ta, and Sn is joined
to a sputtering target material 1 by a metal
bonding agent 5 made of In so as to be
formed into a clad target material 6. The Cu
sheet 4 of this clad target material 6 is
attached to a backing plate 3 consisting of
a Cu sheet with high thermal conductivity
by means of an annular mounting fixture 2.
By this method, the diffusion of the Cu
sheet 4 of the clad target 6 into the backing
plate 3 composed of Cu sheet in the course
of sputtering and the resulting thermal
adhesion between them can be prevented,
by which the separation of the clad target 6
from the backing plate 3 is facilitated and,
as a result, the exchanging operation of the
target 6 can be facilitated.



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